ASSOCIATION CONNECTINE ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Form Typ Distribute					* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mfg Information				
Supplier Inform	ation														
Company name*			Company unique ID				Unique ID Authority					Response Date*			
nsemi											2025-08-23				
Contact Name			Title - Contact				Phone - Contact*				Email - Contact*				
Product-Env-Stewa	rds		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized Represe	ntative*		Title - Representative				Phone - Representative*				Email - Representative*				
Product-Env-Stewa	rds		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requeste	Requester Item Number Mfr Item		rem Number Mfr Item Name			<u> </u>	Effective Dat	e Versi	on	Manufacturing Site		Weight*	UOM	Unit Type	
		KDT00030ATR ALS CHIPLED		ALS CHIPLED S	MD ILK 1001	D ILK 100NA 202				EVERLGFG		1.284	mg	Each	
	Proccess Informatio							,			1		·		
· ·					J-STD-020 M	SL Rating		cess Body	ess Body Temperature Max Time at Peak				per of Reflow Cyc	eles	
Matte Tir	n (Sn) - annealed	C	U Alloy		3		260		C	30	secor	nds 3			
omments															
TTENTION: MSL	3 Rated item requires B	ake and D	ry Pack (after	r electrical test)											
or more informatio	on regarding material cor	nposition p	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure it accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have not written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides										
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the					

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight Unit of Measure		Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.35	mg	Supplier	Silicon (Si)	7440-21-3		0.35	mg
Die Attach	0.05	mg	Supplier	Silver (Ag)	7440-22-4		0.0435	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		0.0065	mg
Mold Compound-Black	0.4	mg	Supplier	1,2,3,6-Tetrahydrophthalic acid anhydride	85-43-8		0.16	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.24	mg
PCB	0.474	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.004	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3		0.354	mg
			Supplier	Gold (Au)	7440-57-5		0.001	mg
			Supplier	Copper (Cu)	7440-50-8		0.1121	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7		0.003	mg
Wire Bond - Au	0.01	mg	Supplier	Gold (Au)	7440-57-5		0.01	mg